Title (en)

CIRCUIT WRITER

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Application

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Priority

- US 19252388 A 19880511
- US 19329188 A 19880511

Abstract (en)

[origin: WO8911209A1] An apparatus, method, and polymerizable material are disclosed for preparing electrically conductive traces on a circuit board (627) (Fig. 11) using an additive technology. The traces (637, Fig. 12a, typical) directly written in a serial process with each trace being able to be individually insulated. The apparatus includes an extrusion element (35 and 37), (Fig. 1) for extruding a first polymerizable material and a stage. The stage (21 and 23) is for holding the extrusion element and the circuit board (41) in relative proximity and for producing relative motion between the extrusion element and the circuit board. According to the method of invention, the first polymerizable material is extruded onto a circuit substrate support (631), (Fig. 12c) along preselected paths to form traces (637, 639, 641 and 643) and the first polymerizable material is polymerized, the first polymerizable material being conductive after polymerization. Several embodiments of extrusion systems are described as are systems for milling and drilling boards to provide new manufactures of circuit boards.

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IPC 8 full level

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Citation (search report)

- US 4743465 A 19880510 - SAEKI KEIJI [JP], et al
- US 4654956 A 19870407 - REED RONALD G [US], et al
- See references of WO 8911209A1

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